


Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.35mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.33mm.
- 5) PAD Cu DIAMETER: 0.457mm.
- 6) SUBSTRATE MATERIAL: BT (ALTERNATE FR4).
- 7) DUMMY DIE IS OPTIONAL.
- 8) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

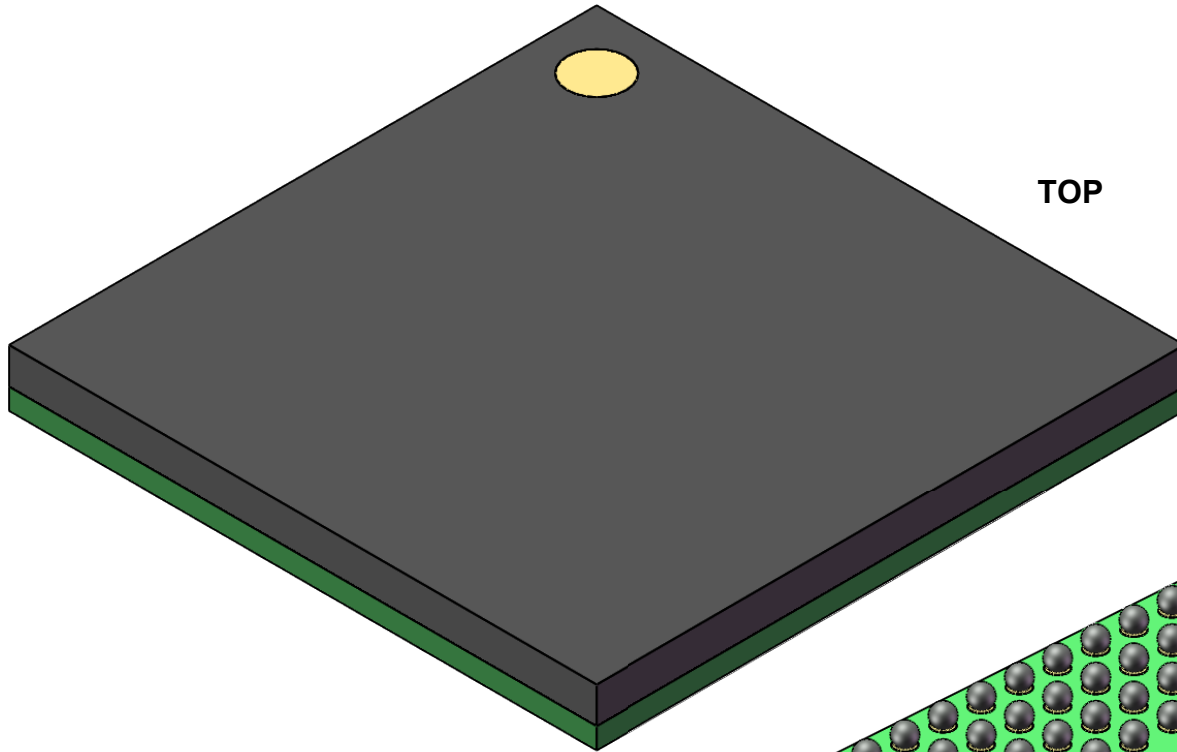
PART NUMBER TABLE

PART NUMBER	BALL ALLOY	Pb-Free	RoHS	Si DIE
BGA176T.65C-15x15-D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA176T.65-15x15-D	Sn63/Pb37	NO	NO	YES

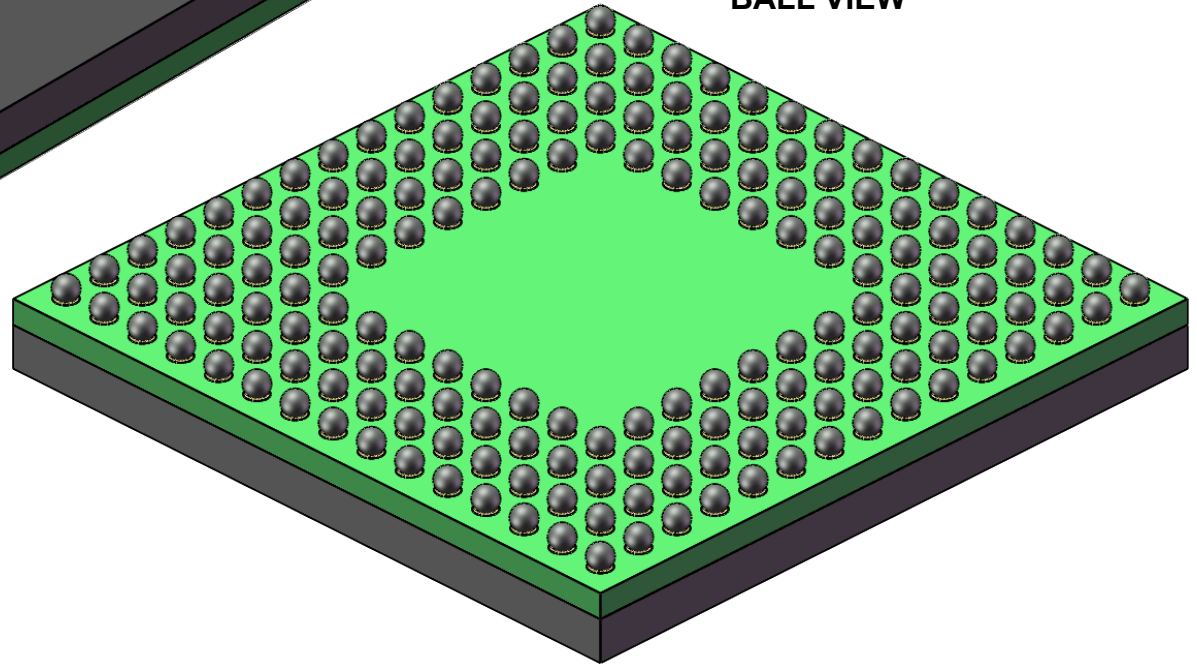
APPROVALS		DATE				
DRAWN	T. Au	8/30/2019				
ENG	M. Hart	8/30/2019	TITLE			
MFG			BGA176T.65-15x15-D			
QA			SCALE	SIZE	DRAWING NO.	REV
CUST			5:1	A	561530	A
REVISED			DO NOT SCALE DRAWING			SHEET 1 OF 2

**MODEL**

**TOP**



**BALL VIEW**



**TopLine**<sup>®</sup>

TITLE			
BGA176T.65-15x15-D			
SCALE	SIZE	DRAWING NO.	REV
5:1	A	561530	A
DO NOT SCALE DRAWING			SHEET 2 OF 2